

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2988929

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JIN YOUNG KIM	07/24/2014
JI YOUNG CHUNG	07/25/2014
DOO HYUN PARK	07/24/2014
CHOON HEUNG LEE	07/30/2014
RECEIVING PARTY DATA	
Name:	AMKOR TECHNOLOGY INC
Street Address:	1900 SOUTH PRICE ROAD
City:	CHANDLER
State/Country:	ARIZONA
Postal Code:	85286-6604
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14449654
CORRESPONDENCE DATA	
Fax Number:	(312)775-8100
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	312.775.8000
Email:	mhmpto@mcandrews-ip.com
Correspondent Name:	MCANDREWS HELD & MALLOY
Address Line 1:	500 W MADISON ST
Address Line 2:	FLOOR 34
Address Line 4:	CHICAGO, ILLINOIS 60661
ATTORNEY DOCKET NUMBER:	27844US02
NAME OF SUBMITTER:	ERICK J. MICHEL
SIGNATURE:	/Erick J. Michel/
DATE SIGNED:	08/20/2014
Total Attachments: 5	
source=27844US02_Assignment_As_Filed#page1.tif	
source=27844US02_Assignment_As_Filed#page2.tif	

source=27844US02_Assignment_As_Filed#page3.tif

source=27844US02_Assignment_As_Filed#page4.tif

source=27844US02_Assignment_As_Filed#page5.tif

ASSIGNMENT

File No.:	27844US02	Serial No.:	14/449,654
Inventors:	Jin Young Kim Ji Young Chung Doo Hyun Park Choon Heung Lee	Filing Date:	August 1, 2014

For good and valuable consideration, the receipt and sufficiency whereof are hereby acknowledged, each of the undersigned hereby assigns to Amkor Technology, Inc., incorporated under the laws of the state of Delaware, its successors and assigns, the entire right, title and interest in the invention or improvements of the undersigned disclosed in an application for Letters Patent of the United States, entitled "A SEMICONDUCTOR DEVICE WITH REDISTRIBUTION LAYERS FORMED UTILIZING DUMMY SUBSTRATES" and identified as File No. 27844US02, in the offices of McANDREWS, HELD & MALLOY, LTD., and in said application and any and all other applications, both United States and foreign, which the undersigned may file, either solely or jointly with others, on said invention or improvements, and in any and all Letters Patent of the United States and foreign countries, which may be obtained on any of said applications, and in any continuation, continuation-in-part, divisional, re-examination, reissue or extension of such patents, and further assigns to said assignee the priority right provided by the International Convention.

Each of the undersigned hereby authorizes and requests the Commissioner of Patents and Trademarks to issue said Letters Patent to said assignee.

Each of the undersigned hereby authorizes and requests the attorneys of record in said application to insert in this assignment the filing date and serial number of said application when officially known.

Each of the undersigned warrants himself/herself to be the owner of the entire right, title and interest in said invention or improvements and to have the right to make this assignment, and further warrants that there are no outstanding prior assignments, licenses, or other encumbrances on the interest herein assigned.

For said considerations, each of the undersigned hereby agrees, upon the request and at the expense of said assignee, its successors and assigns, to execute any and all continuation, continuation-in-part, divisional, re-examination, extension, and substitute applications for said invention or improvements, and any necessary oath, affidavit or declaration relating thereto, and any application for the reissue, re-examination, or extension of any Letters Patent that may be granted upon said application, and any and all applications and other document for Letters Patent in foreign countries on said invention or improvements, that said assignee, its successors or assigns may deem necessary or expedient, and for the said considerations each of the undersigned authorizes said assignee to apply for patents for said invention or improvements in its own name in such countries where such procedure is proper and further agrees, upon the request of said

assignee, its successors and assigns, to cooperate to the best of the ability of the undersigned with said assignee, its successors and assigns, in any proceedings or transactions involving such applications or patents, including the preparation and execution of preliminary statements, giving and producing evidence and performing any and all other acts necessary to obtain or enforce said Letters Patent, both United States and foreign, and vest all rights therein hereby conveyed in the assignee, its successors and assigns, whereby said Letters Patent will be held and enjoyed by the said assignee, its successors and assigns, to the full end of the term for which said Letters Patent will be granted, as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment had not been made. This obligation to cooperate exists both during and after the undersigned's employment.

In the event the assignee is unable to secure the undersigned's signature on any document required by the assignee under this agreement or any document necessary to apply for, establish, prosecute, obtain, or enforce any patent, copyright, or other right or protection relating to said inventions or improvements, whether due to mental or physical incapacity or other cause, the undersigned hereby irrevocably designates and appoints the assignee and each of its duly authorized officers and agents as his or her agent and attorney-in-fact, to act for and in his or her behalf and stead to execute and file any documents and to do all other lawfully permitted acts to further prosecution, issuance, and enforcement of patents, copyrights, or other rights or protections relating to said inventions or improvements with the same force and effect as if executed and delivered by the undersigned.

Executed this 24 day of July, 2014.

Kim Jin Young
Jin Young Kim

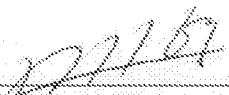
Witnessed By:

[Signature]
Signature

July 24, 2014
Date

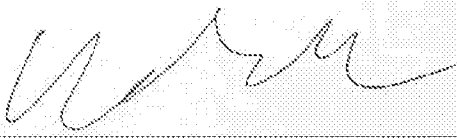
Dohyun Na
Printed Name

Executed this 25 day of Jul, 2014.



Ji Young Chung

Witnessed By:



Signature

July 25, 2014

Date

Do Hyun Na

Printed Name

Executed this 24 day of July, 2014.

Doo Hyun Park
Doo Hyun Park

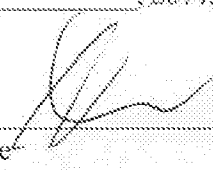
Witnessed By:

U. R. Park
Signature

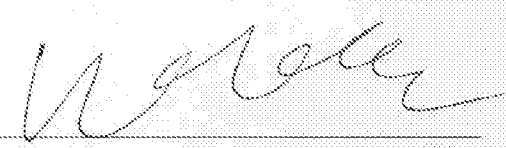
July 24, 2014
Date

Doo Hyun Na
Printed Name

Executed this 30 day of July, 2014.


Choon Heung Lee

Witnessed By:


Signature

July 30, 2014
Date

Dohyun Na
Printed Name